**What Is Claimed Is:**

1. A system for integrating circuitry on an isolation layer, comprising:

a plurality of isolation substrates, each isolation substrate having a circuit deposition region and a substrate-combining region;

a plurality of circuits formed on the circuit deposition regions;

a plurality of substrate-connecting elements formed to connect the substrate-combining regions; and

a plurality of electrical connecting elements formed to electrically connect the circuits formed on the different circuit deposition regions.

2. The system as claimed in claim 1, wherein the substrate-connecting elements are formed by heat fusing or laser.

3. The system as claimed in claim 1, wherein the electrical connecting elements are flex print cables or gold lines.

4. The system as claimed in claim 1, wherein the electrical connecting elements are formed by laser fusing.

5. The system as claimed in claim 1, wherein the materials of the isolation substrates are different.

6. The system as claimed in claim 1, wherein the circuit deposition region contacts the substrate-combining region on different planes.

7. The system as claimed in claim 1, wherein the materials of the isolation substrates are plastic or glass.

8. A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate including a first circuit deposition region and a first substrate-combining region, and a second isolation substrate including a second circuit deposition region and a second substrate-combining region;

forming a first circuit and a second circuit respectively on the first circuit deposition region and the second circuit deposition region;

forming a plurality of substrate-connecting elements for connecting the first substrate-combining region to the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the first circuit and the second circuit.

9. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the substrate-connecting elements are formed by heat fusing or laser.

10. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are flex print cables or gold lines.

11. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are formed by laser fusing.

12. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the first circuit and the second circuit are packed by different packaging methods.

13. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate is plastic.

14. The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate are glass.

15. A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate and a second isolation substrate respectively including a first circuit deposition region and a second circuit deposition region;

forming a plurality of first circuits and a plurality of second circuits respectively on the first circuit deposition region and the second circuit deposition region;

cutting the first isolation substrate and the second isolation substrate, wherein the cut first isolation substrate comprises single first circuit and a first substrate-combining region, and the cut second isolation substrate comprises a single second circuit and a second substrate-combining region;

forming a plurality of substrate-connecting elements for connecting the cut first isolation substrate to the cut second isolation substrate, wherein the first substrate-combining region contacts the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the single first circuit and the single second circuit.

16. The method for integrating a system on an isolation layer as claimed in claim 15, wherein the substrate-connecting elements are formed by heat fusing or laser.

17. The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are flex print cables or gold lines.

18. The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are formed by laser fusing.

19. The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the first isolation substrate is plastic.

20. The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the second isolation substrate is glass.